



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



PRODUCT NUMBER
76350-YXX-XXLF

- RoHS COMPLIANT & COMPATIBLE, SEE NOTE 8
- TOTAL NB OF POSITIONS 04 TO 72
- PIN STYLE SEE SHEET 2

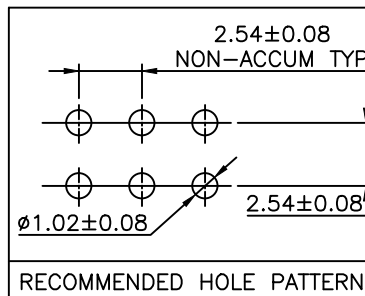
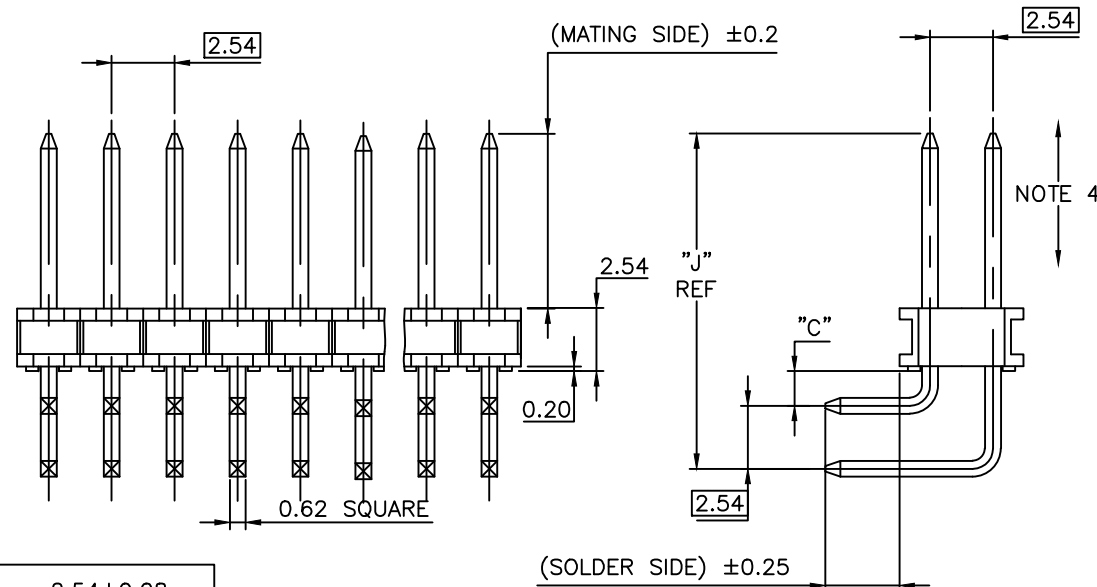
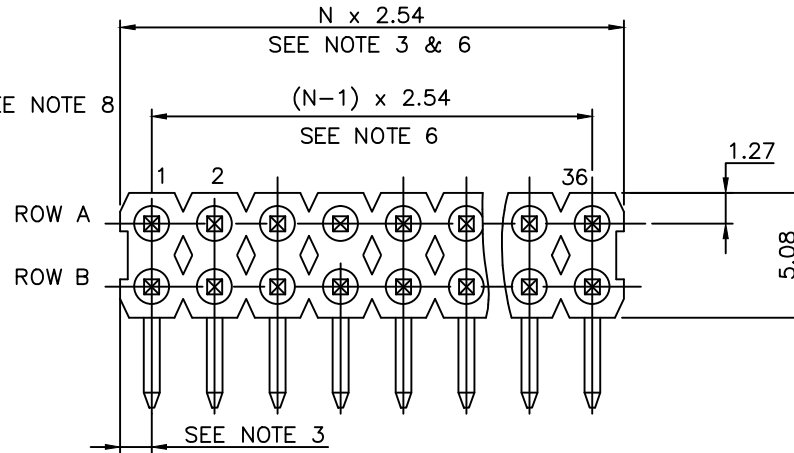
PLATING:

- 1 = 0.76µm FULL GOLD/GXT
- 3 = 2µm MIN MATTE TIN FULL PLATED
- 8 = 0.38µm FULL GOLD/GXT
- 1.27µm Ni MIN UNDERPLATING

NOTES:

1. HOUSING MAT'L : HIGH TEMPERATURE THERMOPLASTIC FLAME RETARDANT PER UL94-V0, COLOR BLACK.
2. PIN MATERIAL : PHOSPHOR BRONZE.
3. DIM 1.27^{+0.03}/_{-0.13} FOR MOULDED SIDE(S) ONLY. IF SIDE(S) ARE BROKEN, DIM 1.02 TO 1.7 MAX APPLIES.
4. PIN PUSH OUT FORCE : 12N MIN.
5. PRODUCT PACKAGED IN POLY BAGS.
6. TO DETERMINE DIMENSIONS :
N = NUMBER OF POSITIONS
EXAMPLE : 8 POS N x 2.54 = 20.32mm
7. FOR STANDARD SELECTIVE GOLD PLATED PRODUCTS, SEE DRAWING 77317.
8. RoHS COMPATIBLE PRODUCT SPECIFICATIONS

- a - LF MEANS THE PRODUCT IS LEAD-FREE
- b - MANUFACTURING PROCESS COMPATIBILITY
 - THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C ±5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.
- c - LABELING:
 - MEETS PACKAGING SPECS AS PER GS-14-920
- d - LEGAL STATEMENT: SEE GS-47-0004



mat'l. code		surface		tolerance		projection		product family	
SEE NOTES		ISO 1302		ISO 406 ISO 1101		mm		BERGSTIK	
tolerances unless otherwise specified		angles		.X ±0.3		mm		title	
lfr	ecn no dr date	linear		.XX ±0.15		scale 5:1		HEADER RA,DR 2.54mm	
AH F06-0207	LMU 06.07.27			.XXX ±0.05				dwg no	
AJ F08-0148	JCO 08.05.27							sheet 1 of 2 size	
AK F11-0077	LMU 11.06.28							76350 A3	
AL B-19261	LMU 14.10.31	dr G LEOTY		95.08.26				type	
AF F03-0203	LMU 03.04.28	engr COMPAGNON J		95.08.26				CUSTOMER Drawing	
AG F02-0186	LMU 05.06.09	appd JMC		95.08.26					
sheet index	revision sheet	AL	AG						
	1 2								

RECOMMENDED HOLE PATTERN

scale 5:1		FCJ	
dwg no		sheet 1 of 2 size	
76350		A3	
type		CUSTOMER Drawing	

APPLICATION SPECIFIC					
PIN	STYLE	MATING	SOLDER	"C"	"J"
03		5.84	2.41	1.52	12.44
04		5.84	3.05	1.52	12.44
06		10.72	13.39	1.52	17.32
07		12.32	13.39	1.52	18.92
08		3.05	3.05	1.52	9.65
09		6.04	1.6	1.52	12.64
10		10.89	3.05	1.52	17.49
14		5.82	7.8	1.4	12.3
15		3.2	10	1.52	9.8
18		3.5	6.4	1.4	10
20		13	3.23	1.52	19.6
22		7.48	1.6	1.52	14.08



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mat'l. code		surface		tolerance		projection		product family	
		ISO 1302 <input checked="" type="checkbox"/>		ISO 406 ISO 1101				BSTIK	
ltr		ecn no	dr	date		tolerances unless otherwise specified		title	
AA	F00135	DLE		00.02.23		angles linear		HEADER,DR,RA, 2.54 mm	
AB	F00145	LMU		00.03.07		mm			
AC	F00461	LMU		00.07.11		scale			
AD	F20116	DLE	02.01.17	dr	G LEOTY	95.08.26	dwg no		sheet 2 of - size
AE	F03-0203	LMU	03.04.28	enfr	COMPAGNON J	95.08.26	76350		A3
AF	F05-0186	LMU	05.06.09	chr			type		CUSTOMER Drawing
AG	F06-0207	LMU	06.07.27	appd	JMC	95.08.26			
sheet	revision								
index	sheet								